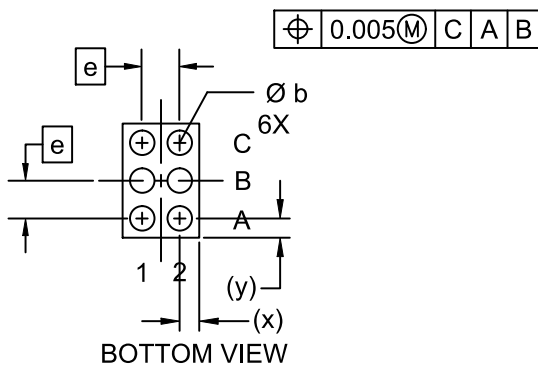
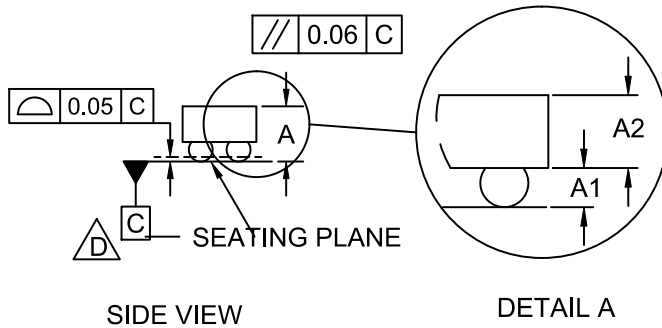
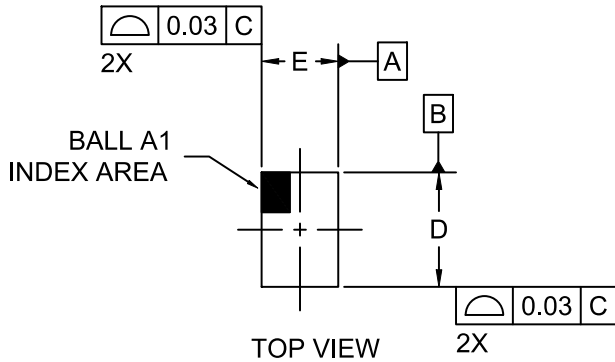




**WLCSP6 1.3x0.9x0.574**  
CASE 567UV  
ISSUE O

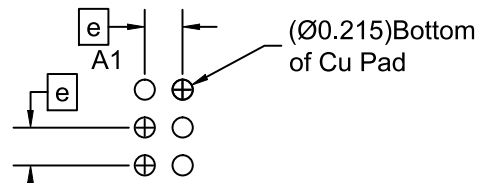
DATE 05 JUL 2017



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DATUM C APPLIES TO THE SPHERICAL CROWN OF THE SOLDER BALLS

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.536	0.574	0.612
A1	0.176	0.196	0.216
A2	0.360	0.378	0.396
b	0.240	0.260	0.280
D	1.270	1.300	1.330
E	0.870	0.900	0.930
e	0.40 BSC		
x	0.235	0.250	0.265
y	0.235	0.250	0.265



RECOMMENDED  
MOUNTING FOOTPRINT  
(NSMD PAD TYPE)

<b>DOCUMENT NUMBER:</b>	<b>98AON66547G</b>	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
<b>DESCRIPTION:</b>	<b>WLCSP6 1.3x0.9x0.574</b>	<b>PAGE 1 OF 1</b>

ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.